Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	2016
Number of Logic Elements/Cells	-
Total RAM Bits	18432
Number of I/O	168
Number of Gates	125000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 70°C (TA)
Package / Case	324-BGA
Supplier Device Package	324-FBGA (19x19)
Purchase URL	https://www.e-xfl.com/product-detail/microsemi/ax125-2fg324

The maximum power dissipation allowed for Military temperature and Mil-Std 883B devices is specified as a function of θ_{jc}.

Table 2-6 • **Package Thermal Characteristics**

Package Type	Pin Count	θ_{jc}	θ_{ja} Still Air	θ_{ja} 1.0m/s	θ_{ja} 2.5m/s	Units
Chip Scale Package (CSP)	180	N/A	57.8	51.0	50	°C/W
Plastic Quad Flat Pack (PQFP)	208	8.0	26	23.5	20.9	°C/W
Plastic Ball Grid Array (PBGA)	729	2.2	13.7	10.6	9.6	°C/W
Fine Pitch Ball Grid Array (FBGA)	256	3.0	26.6	22.8	21.5	°C/W
Fine Pitch Ball Grid Array (FBGA)	324	3.0	25.8	22.1	20.9	°C/W
Fine Pitch Ball Grid Array (FBGA)	484	3.2	20.5	17.0	15.9	°C/W
Fine Pitch Ball Grid Array (FBGA)	676	3.2	16.4	13.0	12.0	°C/W
Fine Pitch Ball Grid Array (FBGA)	896	2.4	13.6	10.4	9.4	°C/W
Fine Pitch Ball Grid Array (FBGA)	1152	1.8	12.0	8.9	7.9	°C/W
Ceramic Quad Flat Pack (CQFP)[1]	208	2.0	22	19.8	18.0	°C/W
Ceramic Quad Flat Pack (CQFP)[1]	352	2.0	17.9	16.1	14.7	°C/W
Ceramic Column Grid Array (CCGA)[2]	624	6.5	8.9	8.5	8	°C/W

Notes:

1. *θ_{jc} for the 208-pin and 352-pin CQFP refers to the thermal resistance between the junction and the bottom of the package.*
2. *θ_{jc} for the 624-pin CCGA refers to the thermal resistance between the junction and the top surface of the package. Thermal resistance from junction to board (θ_{jb}) for CCGA 624 package is 3.4°C/W.*

Timing Characteristics

Axcelerator devices are manufactured in a CMOS process, therefore, device performance varies according to temperature, voltage, and process variations. Minimum timing parameters reflect maximum operating voltage, minimum operating temperature, and best-case processing. Maximum timing parameters reflect minimum operating voltage, maximum operating temperature, and worst-case processing. The derating factors shown in Table 2-7 should be applied to all timing data contained within this datasheet.

Table 2-7 • **Temperature and Voltage Timing Derating Factors (Normalized to Worst-Case Commercial, T_J = 70°C, VCCA = 1.425V)**

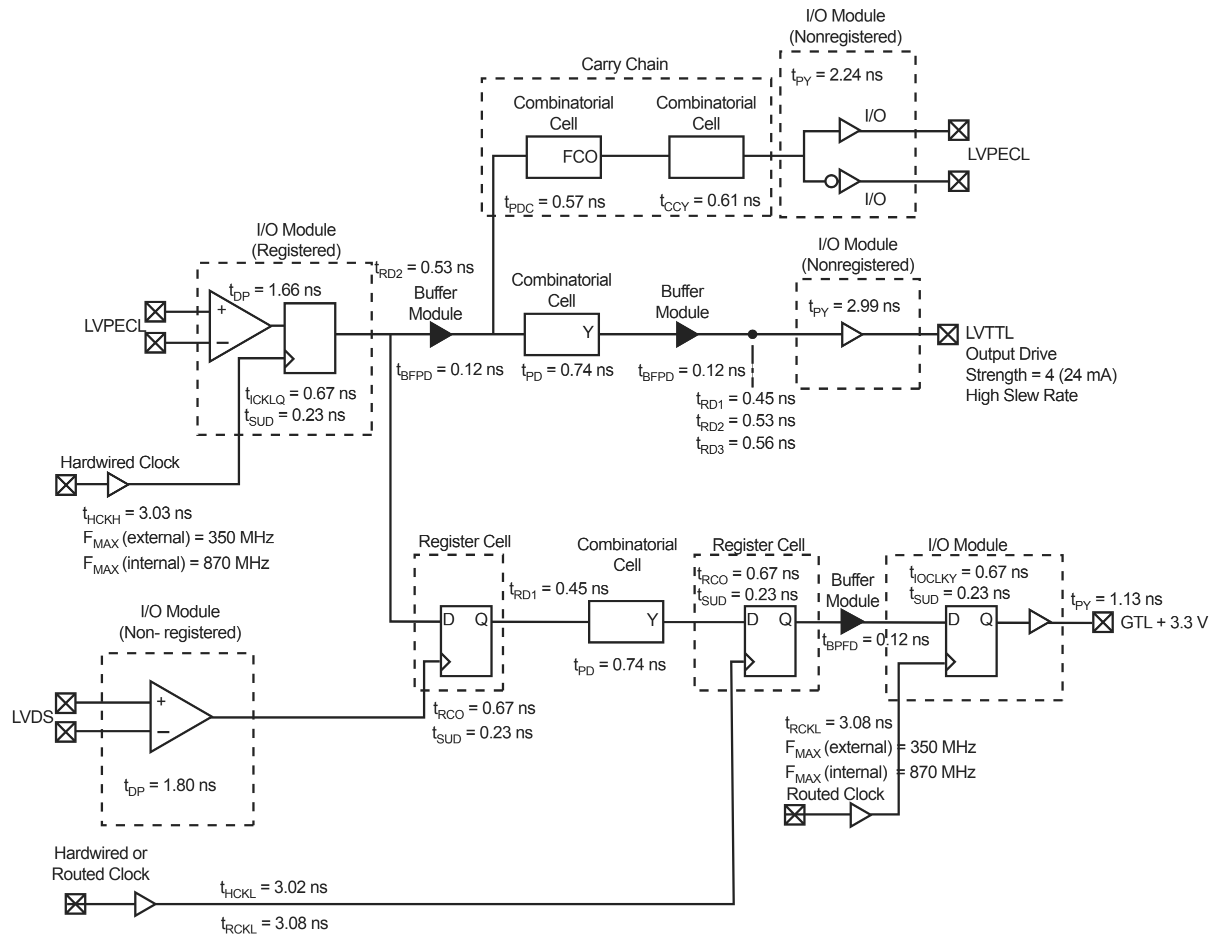
VCCA	Junction Temperature						
	–55°C	–40°C	0°C	25°C	70°C	85°C	125°C
1.4 V	0.83	0.86	0.91	0.96	1.02	1.05	1.15
1.425 V	0.82	0.84	0.90	0.94	1.00	1.04	1.13
1.5 V	0.78	0.80	0.85	0.89	0.95	0.98	1.07
1.575 V	0.74	0.76	0.81	0.85	0.90	0.94	1.02
1.6 V	0.73	0.75	0.80	0.84	0.89	0.92	1.01

Notes:

1. *The user can set the junction temperature in Designer software to be any integer value in the range of –55°C to 175°C.*
2. *The user can set the core voltage in Designer software to be any value between 1.4V and 1.6V.*

All timing numbers listed in this datasheet represent sample timing characteristics of Axcelerator devices. Actual timing delay values are design-specific and can be derived from the Timer tool in Microsemi’s Designer software after place-and-route.

Timing Model



Note: Worst case timing data for the AX1000, –2 speed grade

Figure 2-1 • **Worst Case Timing Data**

Hardwired Clock – Using LVTTL 24 mA High Slew Clock I/O

External Setup

$= (t_{DP} + t_{RD2} + t_{SUD}) - t_{HCKL}$

$= (1.72 + 0.53 + 0.23) - 3.02 = -0.54$ ns

Clock-to-Out (Pad-to-Pad)

$= t_{HCKL} + t_{RCO} + t_{RD1} + t_{PY}$

$= 3.02 + 0.67 + 0.45 + 2.99 = 7.13$ ns

Routed Clock – Using LVTTL 24 mA High Slew Clock I/O

External Setup

$= (t_{DP} + t_{RD2} + t_{SUD}) - t_{RCKH}$

$= (1.72 + 0.53 + 0.23) - 3.13 = -0.65$ ns

Clock-to-Out (Pad-to-Pad)

$= t_{RCKH} + t_{RCO} + t_{RD1} + t_{PY}$

$= 3.13 + 0.67 + 0.45 + 3.03 = 7.24$ ns

Table 2-8 • I/O Standards Supported by the Axcelerator Family

I/O Standard	Input/Output Supply Voltage (VCCI)	Input Reference Voltage (VREF)	Board Termination Voltage (VTT)
LVTTL	3.3	N/A	N/A
LVCMOS 2.5 V	2.5	N/A	N/A
LVCMOS 1.8 V	1.8	N/A	N/A
LVCMOS 1.5 V (JDEC8-11)	1.5	N/A	N/A
3.3V PCI/PCI-X	3.3	N/A	N/A
GTL+ 3.3 V	3.3	1.0	1.2
GTL+ 2.5 V*	2.5	1.0	1.2
HSTL Class 1	1.5	0.75	0.75
SSTL3 Class 1 and II	3.3	1.5	1.5
SSTL2 Class1 and II	2.5	1.25	1.25
LVDS	2.5	N/A	N/A
LVPECL	3.3	N/A	N/A

*Note: *2.5 V GTL+ is not supported across the full military temperature range.*

Table 2-9 • Supply Voltages

VCCA	VCCI	Input Tolerance	Output Drive Level
1.5 V	1.5 V	3.3 V	1.5 V
1.5 V	1.8 V	3.3 V	1.8 V
1.5 V	2.5 V	3.3 V	2.5 V
1.5 V	3.3 V	3.3 V	3.3 V

Table 2-10 • I/O Features Comparison

I/O Assignment	Clamp Diode	Hot Insertion	5 V Tolerance	Input Buffer	Output Buffer
LVTTL	No	Yes	Yes[1]	Enabled/Disabled	
3.3 V PCI, 3.3 V PCI-X	Yes	No	Yes[1, 2]	Enabled/Disabled	
LVCMOS 2.5 V	No	Yes	No	Enabled/Disabled	
LVCMOS 1.8 V	No	Yes	No	Enabled/Disabled	
LVCMOS 1.5 V (JESD8-11)	No	Yes	No	Enabled/Disabled	
Voltage-Referenced Input Buffer	No	Yes	No	Enabled/Disabled	
Differential, LVDS/LVPECL, Input	No	Yes	No	Enabled	Disabled[3]
Differential, LVDS/LVPECL, Output	No	Yes	No	Disabled	Enabled[4]

Notes:

1. *Can be implemented with an IDT bus switch.*
2. *Can be implemented with an external resistor.*
3. *The OE input of the output buffer must be deasserted permanently (handled by software).*
4. *The OE input of the output buffer must be asserted permanently (handled by software).*

Using the Weak Pull-Up and Pull-Down Circuits

Each Axcelerator I/O comes with a weak pull-up/down circuit (on the order of 10 kΩ). These are weak transistors with the gates tied on, so the on resistance of the transistor emulates a resistor. The weak pull-up and pull-down is active only when the device is powered up, and they must be biased to be on. When the rails are coming up, they are not biased fully, so they do not behave as resistors until the voltage is at sufficient levels to bias the transistors. The key is they really are transistors; they are not traces of poly silicon, which is another way to do an on-chip resistor (those take much more room). I/O macros are provided for combinations of pull up/down for LVTTL, LVCMOS (2.5 V, 1.8 V, and 1.5 V) standards. These macros can be instantiated if a keeper circuit for any input buffer is required.

Customizing the I/O

- A five-bit programmable input delay element is associated with each I/O. The value of this delay is set on a bank-wide basis (Table 2-14). It is optional for each input buffer within the bank (i.e. the user can enable or disable the delay element for the I/O). When the input buffer drives a register within the I/O, the delay element is activated by default to ensure a zero hold-time. The default setting for this property can be set in Designer. When the input buffer does not drive a register, the delay element is deactivated to provide higher performance. Again, this can be overridden by changing the default setting for this property in Designer.
- The slew-rate value for the LVTTL output buffer can be programmed and can be set to either slow or fast.
- The drive strength value for LVTTL output buffers can be programmed as well. There are four different drive strength values – 8 mA, 12 mA, 16 mA, or 24 mA – that can be specified in Designer.[5]

***Table 2-14* • Bank-Wide Delay Values**

Bits Setting	Delay (ns)	Bits Setting	Delay (ns)
0	0.54	16	2.01
1	0.65	17	2.13
2	0.71	18	2.19
3	0.83	19	2.3
4	0.9	20	2.38
5	1.01	21	2.49
6	1.08	22	2.55
7	1.19	23	2.67
8	1.27	24	2.75
9	1.39	25	2.87
10	1.45	26	2.93
11	1.56	27	3.04
12	1.64	28	3.12
13	1.75	29	3.23
14	1.81	30	3.29
15	1.93	31	3.41

Note: Delay values are approximate and will vary with process, temperature, and voltage.

5. *These values are minimum drive strengths.*

1.8 V LVCMOS

Low-Voltage Complementary Metal-Oxide Semiconductor for 1.8 V is an extension of the LVCMOS standard (JESD8-5) used for general-purpose 1.8 V applications. It uses a 3.3 V tolerant CMOS input buffer and a push-pull output buffer.

***Table 2-26* • DC Input and Output Levels**

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	**Max., V**	**Min., V**	**Max., V**	**Max., V**	**Min., V**	**mA**	**mA**
–0.3	0.2 VCCI	0.7 VCCI	3.6	0.2	VCCI – 0.2	8 mA	–8 mA

AC Loadings

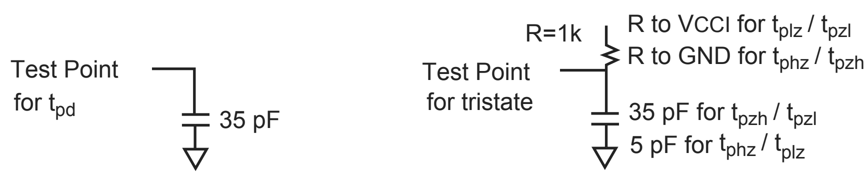


***Figure 2-17* • AC Test Loads**

***Table 2-27* • AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C_{load} (pF)
0	1.8	0.5 VCCI	N/A	35

*Note: * Measuring Point = VTRIP*

Timing Characteristics

Table 2-28 • 1.8V LVCMOS I/O Module
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 1.7 V, TJ = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVCMOS18 Output Module Timing								
t_{DP}	Input Buffer		3.26		3.71		4.37	ns
t_{PY}	Output Buffer		4.55		5.18		6.09	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		2.82		2.83		2.84	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		3.43		3.45		3.46	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		6.01		6.85		8.05	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		6.73		7.67		9.01	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Timing Characteristics

Table 2-32 • 1.5V LVCMOS I/O Module
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 1.4 V, TJ = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVCMOS15 (JESD8-11) I/O Module Timing								
t_{DP}	Input Buffer		3.59		4.09		4.81	ns
t_{PY}	Output Buffer		6.05		6.89		8.10	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		3.31		3.34		3.34	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		4.56		4.58		4.59	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		6.37		7.25		8.52	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		6.94		7.90		9.29	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

R-Cell

Introduction

The R-cell, the sequential logic resource of the Axcelerator devices, is the second logic module type in the AX family architecture. It includes clock inputs for all eight global resources of the Axcelerator architecture as well as global presets and clears (Figure 2-31).

The main features of the R-cell include the following:

- Direct connection to the adjacent logic module through the hardwired connection DCIN. DCIN is driven by the DCOUT of an adjacent C-cell via the Direct-Connect routing resource, providing a connection with less than 0.1 ns of routing delay.
- The R-cell can be used as a standalone flip-flop. It can be driven by any C-cell or I/O modules through the regular routing structure (using DIN as a routable data input). This gives the option of using the R-Cell as a 2:1 MUXed flip-flop as well.
- Provision of data enable-input (S0).
- Independent active-low asynchronous clear (CLR).
- Independent active-low asynchronous preset (PSET). If both CLR and PSET are low, CLR has higher priority.
- Clock can be driven by any of the following (CKP selects clock polarity):
  - One of the four high performance hardwired fast clocks (HCLKs)
  - One of the four routed clocks (CLKs)
  - User signals
- Global power-on clear (GCLR) and preset (GPSET), which drive each flip-flop on a chip-wide basis.
  - When the Global Set Fuse option in the Designer software is unchecked (by default), GCLR = 0 and GPSET = 1 at device power-up. When the option is checked, GCLR = 1 and GPSET = 0. Both pins are pulled High when the device is in user mode. Refer to the "Simulation Support for GCLR/GPSET in Axcelerator" section of the *Antifuse Macro Library Guide* for information on simulation support for GCLR and GPSET.
- S0, S1, PSET, and CLR can be driven by routed clocks CLKE/F/G/H or user signals.
- DIN and S1 can be driven by user signals.

As with the C-cell, the configuration of the R-cell to perform various functions is handled automatically for the user through Microsemi's extensive macro library (see the *Antifuse Macro Library Guide* for a complete listing of available AX macros).

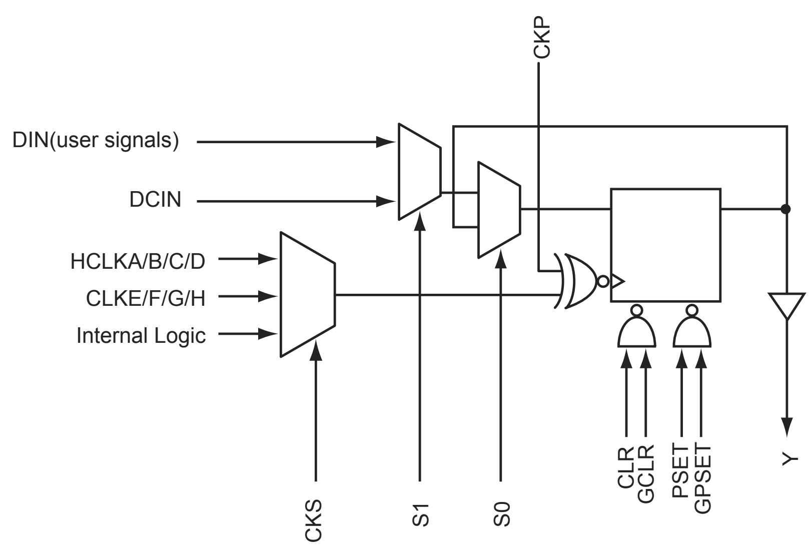


Figure 2-31 **• R-Cell**

The HM and CM modules can select between:

- The HCLK or CLK source respectively
- A local signal routed on generic routing resources

This allows each core tile to have eight clocks independent of the other core tiles in the device.

Both HCLK and CLK are segmentable, meaning that individual branches of the global resource can be used independently.

Like the HM and CM modules, the HD and RD modules can select between:

- The HCLK or CLK source from the HM or CM module respectively
- A local signal routed on generic routing resources

The AX architecture is capable of supporting a large number of local clocks—24 segments per HCLK driving north-south and 28 segments per CLK driving east-west per core tile.

Microsemi's Designer software's place-and-route takes advantage of the segmented clock structure found in Axcelerator devices by turning off any unused clock segments. This results in not only better performance but also lower power consumption.

Global Resource Access Macros

Global resources can be driven by one of three sources: external pad(s), an internal net, or the output of a PLL. These connections can be made by using one of three types of macros: CLKBUF, CLKINT, and PLLCLK.

CLKBUF and HCLKBUF

CLKBUF (HCLKBUF) is used to drive a CLK (HCLK) from external pads. These macros can be used either generically or with the specific I/O standard desired (e.g. CLKBUF_LVCMOS25, HCLKBUF_LVDS, etc.) (Figure 2-42).

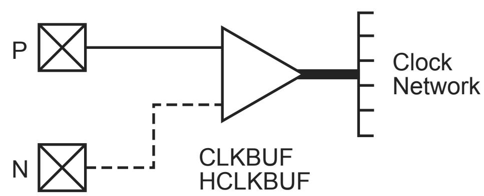


Figure 2-42 **• CLKBUF and HCLKBUF**

Package pins CLKEP and CLKEN are associated with CLKE; package pins HCLKAP and HCLKAN are associated with HCLKA, etc.

Note that when CLKBUF (HCLKBUF) is used with a single-ended I/O standard, it must be tied to the P-pad of the CLK (HCLK) package pin. In this case, the CLK (HCLK) N-pad can be used for user signals.

CLKINT and HCLKINT

CLKINT (HCLKINT) is used to access the CLK (HCLK) resource internally from the user signals (Figure 2-43).

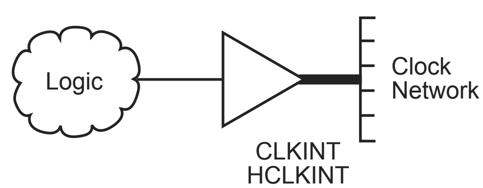


Figure 2-43 **• CLKINT and HCLKINT**

Clock Skew Minimization

Figure 2-56 indicates how feedback from the clock network can be used to create minimal skew between the distributed clock network and the input clock. The input clock is fed to the reference clock input of the PLL. The output clock (CLK2) feeds a routed clock network. The feedback input to the PLL uses a clock input delayed by a routing network. The PLL then adjusts the phase of the input clock to match the delayed clock, thus providing nearly zero effective skew between the two clocks. Refer to the *Axcelerator Family PLL and Clock Management* application note for more information.

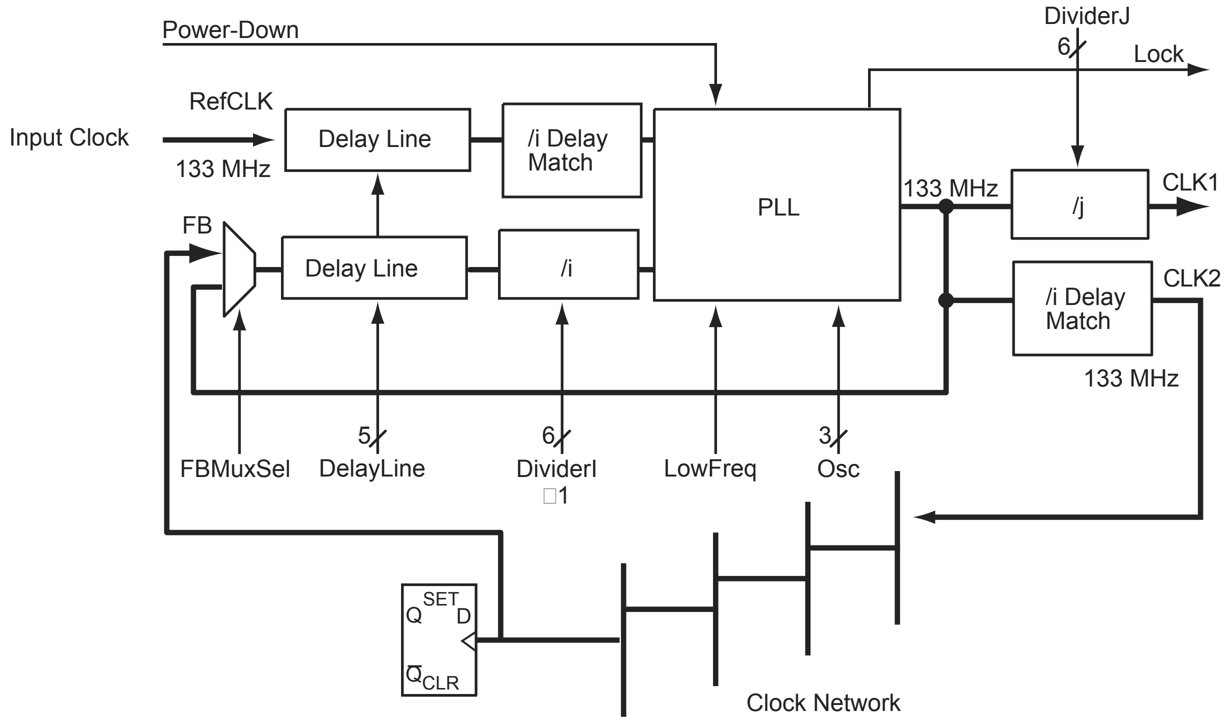


Figure 2-56 • **Using the PLL for Clock Deskewing**

Timing Characteristics

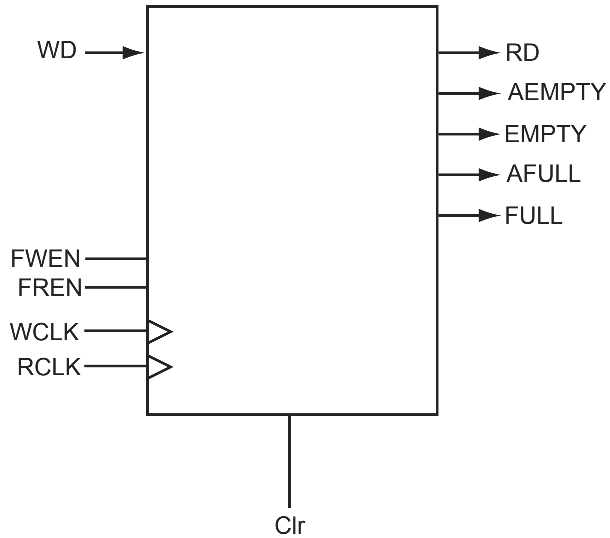


Figure 2-66 • **FIFO Model**

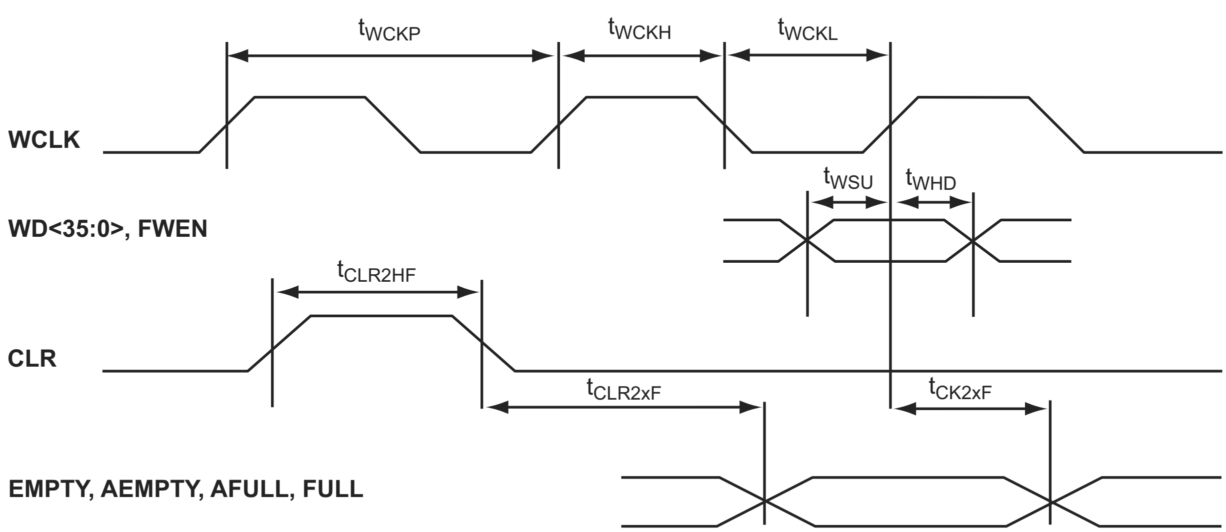


Figure 2-67 • **FIFO Write Timing**

***Table 2-99* • Two FIFO Blocks Cascaded**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
FIFO Module Timing								
t_{WSU}	Write Setup		13.75		15.66		18.41	ns
t_{WHD}	Write Hold		0.00		0.00		0.00	ns
t_{WCKH}	WCLK High		0.75		0.75		0.75	ns
t_{WCKL}	WCLK Low		1.76		1.76		1.76	ns
t_{WCKP}	Minimum WCLK Period	2.51		2.51		2.51		ns
t_{RSU}	Read Setup		14.33		16.32		19.19	ns
t_{RHD}	Read Hold		0.00		0.00		0.00	ns
t_{RCKH}	RCLK High		0.73		0.73		0.73	ns
t_{RCKL}	RCLK Low		1.89		1.89		1.89	ns
t_{RCKP}	Minimum RCLK period	2.62		2.62		2.62		ns
t_{CLRHF}	Clear High		0.00		0.00		0.00	ns
t_{CLR2FF}	Clear-to-flag (EMPTY/FULL)		1.92		2.18		2.57	ns
t_{CLR2AF}	Clear-to-flag (AEMPTY/AFULL)		4.39		5.00		5.88	ns
t_{CK2FF}	Clock-to-flag (EMPTY/FULL)		2.13		2.42		2.85	ns
t_{CK2AF}	Clock-to-flag (AEMPTY/AFULL)		5.04		5.75		6.75	ns
$t_{RCK2RD1}$	RCLK-To-OUT (Pipelined)		1.43		1.63		1.92	ns
$t_{RCK2RD2}$	RCLK-To-OUT (Nonpipelined)		2.26		2.58		3.03	ns

Note: Timing data for these two cascaded FIFO blocks uses a depth of 8,192. For all other combinations, use Microsemi's timing software.

FG324	
AX125 Function	**Pin Number**
VCCIB5	N7
VCCIB5	N8
VCCIB5	N9
VCCIB6	K6
VCCIB6	L6
VCCIB6	M6
VCCIB7	G6
VCCIB7	H6
VCCIB7	J6
VCOMPLA	B8
VCOMPLB	E8
VCOMPLC	C10
VCOMPLD	E12
VCOMPLE	U11
VCOMPLF	P11
VCOMPLG	T9
VCOMPLH	P7
VPUMP	B15

FG484	
AX250 Function	Pin Number
NC	A19
NC	A4
NC	A5
NC	AA11
NC	AA12
NC	AA18
NC	AA19
NC	AA4
NC	AB16
NC	AB17
NC	AB4
NC	AB7
NC	AB8
NC	B11
NC	B12
NC	B17
NC	B18
NC	B19
NC	B4
NC	B5
NC	C10
NC	C11
NC	C14
NC	C15
NC	C18
NC	C19
NC	D1
NC	D2
NC	D21
NC	D3
NC	E1
NC	E2
NC	E21
NC	E3
NC	F22
NC	F3

FG484	
AX250 Function	Pin Number
NC	G22
NC	G3
NC	H3
NC	J3
NC	K21
NC	K22
NC	N22
NC	P22
NC	R19
NC	R22
NC	T1
NC	T22
NC	U1
NC	U2
NC	U21
NC	U22
NC	V1
NC	V2
NC	V21
NC	V22
NC	V3
NC	W1
NC	W2
NC	W21
NC	W22
NC	W3
NC	Y10
NC	Y11
NC	Y12
NC	Y13
NC	Y15
NC	Y16
NC	Y17
NC	Y18
NC	Y8
NC	Y9

FG484	
AX250 Function	Pin Number
PRA	G11
PRB	F11
PRC	T12
PRD	U12
TCK	G8
TDI	F9
TDO	F7
TMS	F6
TRST	F8
VCCA	G17
VCCA	J10
VCCA	J11
VCCA	J12
VCCA	J13
VCCA	J7
VCCA	K14
VCCA	K9
VCCA	L14
VCCA	L9
VCCA	M14
VCCA	M9
VCCA	N14
VCCA	N9
VCCA	P10
VCCA	P11
VCCA	P12
VCCA	P13
VCCA	T6
VCCA	U17
VCCPLA	F10
VCCPLB	G9
VCCPLC	D13
VCCPLD	G13
VCCPLE	U13
VCCPLF	T14
VCCPLG	W10

FG484	
AX1000 Function	**Pin Number**
IO87PB2F8	H20
IO88NB2F8	L18
IO88PB2F8	K18
IO89NB2F8	K19
IO89PB2F8	J19
IO90NB2F8	J21
IO90PB2F8	H21
IO91NB2F8	J22
IO91PB2F8	H22
IO93NB2F8	K21
IO93PB2F8	K22
IO94NB2F8	L20
IO94PB2F8	K20
IO95NB2F8	M21
IO95PB2F8	L21
Bank 3	
IO96NB3F9	N16
IO96PB3F9	M16
IO97NB3F9	M19
IO97PB3F9	L19
IO98NB3F9	P22
IO98PB3F9	N22
IO99NB3F9	N20
IO99PB3F9	M20
IO100NB3F9	N17
IO100PB3F9	M17
IO101NB3F9	P21
IO101PB3F9	N21
IO103NB3F9	R20
IO103PB3F9	P20
IO104NB3F9	N18
IO104PB3F9	N19
IO105NB3F9	T22
IO105PB3F9	R22
IO106NB3F9	R17
IO106PB3F9	P17
IO107NB3F10	T21
IO107PB3F10	R21
IO110NB3F10	V22
IO110PB3F10	U22
IO113NB3F10	V21
IO113PB3F10	U21
IO114NB3F10	P18
IO114PB3F10	P19
IO116PB3F10	R19
IO117NB3F10	U20
IO117PB3F10	T20
IO118NB3F11	T18
IO118PB3F11	R18
IO121NB3F11	U19
IO121PB3F11	T19
IO124NB3F11	R16
IO124PB3F11	P16
IO127NB3F11	W21
IO127PB3F11	W22
Bank 4	
IO129PB4F12	AB17
IO132NB4F12	Y19
IO132PB4F12	W18
IO133NB4F12	W17
IO133PB4F12	V17
IO135NB4F12	T15
IO135PB4F12	T16
IO138NB4F12	Y17
IO138PB4F12	Y18
IO139NB4F13	V15
IO139PB4F13	V16
IO140NB4F13	U18
IO140PB4F13	V19
IO142NB4F13	W20
IO142PB4F13	V20
IO143NB4F13	W15
IO143PB4F13	W16
IO144NB4F13	AA18
IO144PB4F13	AA19
IO145NB4F13	U14
IO145PB4F13	U15
IO146NB4F13	Y15
IO146PB4F13	Y16
IO147NB4F13	AB18
IO147PB4F13	AB19
IO149NB4F13	Y14
IO149PB4F13	W14
IO150NB4F13	AA16
IO150PB4F13	AA17
IO152NB4F14	AA14
IO152PB4F14	AA15
IO154NB4F14	AB14
IO154PB4F14	AB15
IO155NB4F14	AA13
IO155PB4F14	AB13
IO158NB4F14	Y12
IO158PB4F14	Y13
IO159NB4F14/CLKEN	V12
IO159PB4F14/CLKEP	V13
IO160NB4F14/CLKFN	W11
IO160PB4F14/CLKFP	W12
Bank 5	
IO161NB5F15/CLKGN	U10
IO161PB5F15/CLKGP	U11
IO162NB5F15/CLKHN	V9
IO162PB5F15/CLKHP	V10
IO163NB5F15	Y10
IO163PB5F15	Y11
IO167NB5F15	AA11

FG676	
AX500 Function	**Pin Number**
VCCIB3	T19
VCCIB3	U19
VCCIB3	U20
VCCIB3	V19
VCCIB3	V20
VCCIB3	W20
VCCIB4	W14
VCCIB4	W15
VCCIB4	W16
VCCIB4	W17
VCCIB4	W18
VCCIB4	Y17
VCCIB4	Y18
VCCIB4	Y19
VCCIB5	W10
VCCIB5	W11
VCCIB5	W12
VCCIB5	W13
VCCIB5	W9
VCCIB5	Y10
VCCIB5	Y8
VCCIB5	Y9
VCCIB6	P8
VCCIB6	R8
VCCIB6	T8
VCCIB6	U7
VCCIB6	U8
VCCIB6	V7
VCCIB6	V8
VCCIB6	W7
VCCIB7	H7
VCCIB7	J7
VCCIB7	J8
VCCIB7	K7
VCCIB7	K8

FG676	
AX500 Function	**Pin Number**
VCCIB7	L8
VCCIB7	M8
VCCIB7	N8
VCCPLA	E12
VCCPLB	F13
VCCPLC	E15
VCCPLD	G14
VCCPLE	AF15
VCCPLF	AA14
VCCPLG	AF12
VCCPLH	AB13
VCOMPLA	D12
VCOMPLB	G13
VCOMPLC	D15
VCOMPLD	F14
VCOMPLE	AD15
VCOMPLF	AB14
VCOMPLG	AD12
VCOMPLH	Y13
VPUMP	E22

FG676	
AX1000 Function	Pin Number
GND	A8
GND	AC23
GND	AC4
GND	AD24
GND	AD3
GND	AE2
GND	AE25
GND	AF1
GND	AF13
GND	AF14
GND	AF19
GND	AF26
GND	AF8
GND	B2
GND	B25
GND	B26
GND	C24
GND	C3
GND	G20
GND	G7
GND	H1
GND	H19
GND	H26
GND	H8
GND	J18
GND	J9
GND	K10
GND	K11
GND	K12
GND	K13
GND	K14
GND	K15
GND	K16
GND	K17
GND	L10
GND	L11

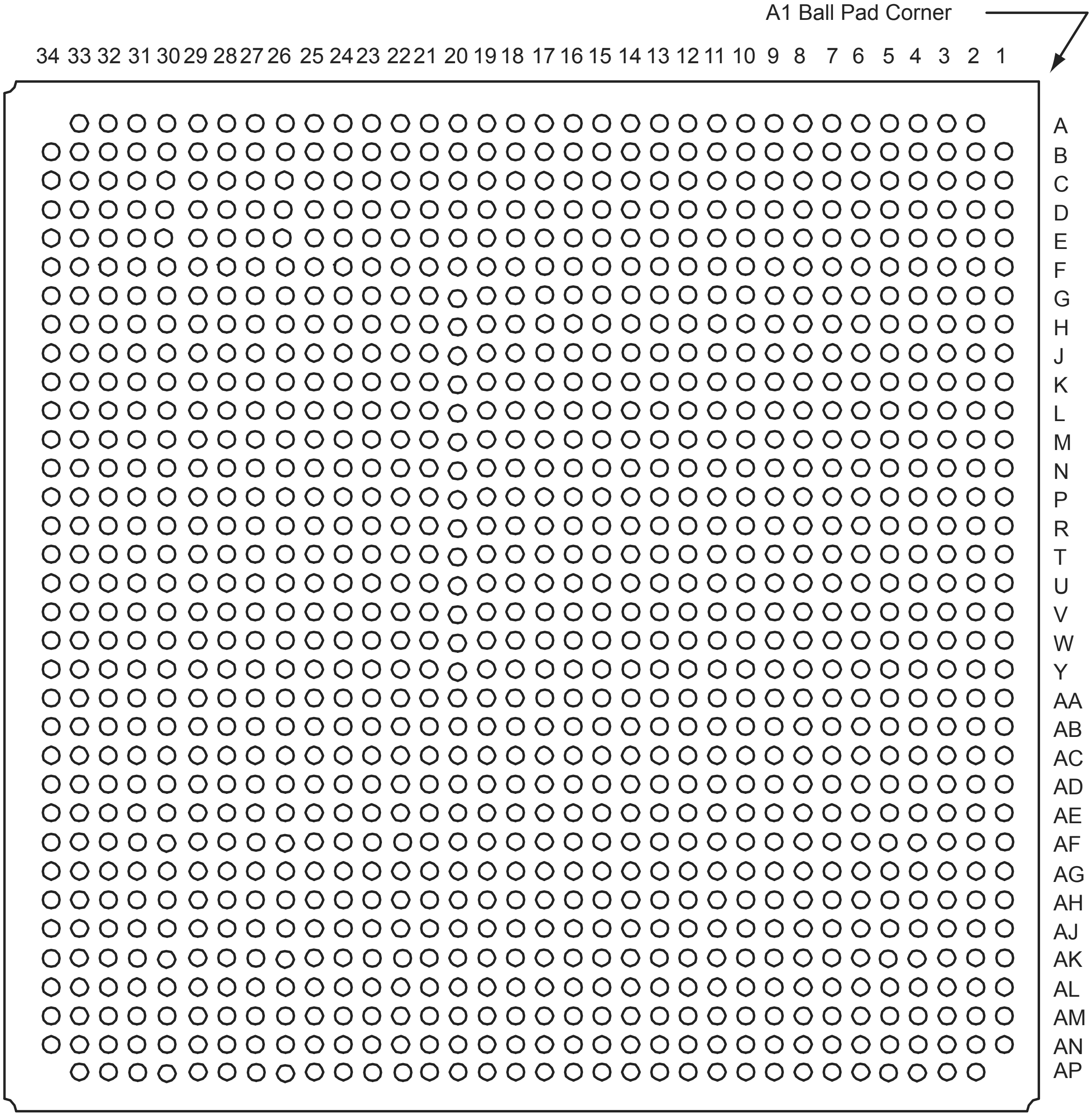
FG676	
AX1000 Function	Pin Number
GND	L12
GND	L13
GND	L14
GND	L15
GND	L16
GND	L17
GND	M10
GND	M11
GND	M12
GND	M13
GND	M14
GND	M15
GND	M16
GND	M17
GND	N1
GND	N10
GND	N11
GND	N12
GND	N13
GND	N14
GND	N15
GND	N16
GND	N17
GND	N26
GND	P1
GND	P10
GND	P11
GND	P12
GND	P13
GND	P14
GND	P15
GND	P16
GND	P17
GND	P26
GND	R10
GND	R11

FG676	
AX1000 Function	Pin Number
GND	R12
GND	R13
GND	R14
GND	R15
GND	R16
GND	R17
GND	T10
GND	T11
GND	T12
GND	T13
GND	T14
GND	T15
GND	T16
GND	T17
GND	U10
GND	U11
GND	U12
GND	U13
GND	U14
GND	U15
GND	U16
GND	U17
GND	V18
GND	V9
GND	W1
GND	W19
GND	W26
GND	W8
GND	Y20
GND	Y7
GND/LP	C2
NC	A25
NC	AC13
NC	AC14
NC	AF2
NC	AF25

FG896	
AX2000 Function	Pin Number
VCCIB3	AH30
VCCIB3	T21
VCCIB3	U21
VCCIB3	V21
VCCIB3	W21
VCCIB3	W22
VCCIB3	Y21
VCCIB3	Y22
VCCIB4	AA16
VCCIB4	AA17
VCCIB4	AA18
VCCIB4	AA19
VCCIB4	AA20
VCCIB4	AB19
VCCIB4	AB20
VCCIB4	AB21
VCCIB4	AJ28
VCCIB4	AK28
VCCIB5	AA11
VCCIB5	AA12
VCCIB5	AA13
VCCIB5	AA14
VCCIB5	AA15
VCCIB5	AB10
VCCIB5	AB11
VCCIB5	AB12
VCCIB5	AJ3
VCCIB5	AK3
VCCIB6	AA9
VCCIB6	AH1
VCCIB6	AH2
VCCIB6	T10
VCCIB6	U10
VCCIB6	V10
VCCIB6	W10

FG896	
AX2000 Function	Pin Number
VCCIB6	W9
VCCIB6	Y10
VCCIB6	Y9
VCCIB7	C1
VCCIB7	C2
VCCIB7	K9
VCCIB7	L10
VCCIB7	L9
VCCIB7	M10
VCCIB7	M9
VCCIB7	N10
VCCIB7	P10
VCCIB7	R10
VCCPLA	G14
VCCPLB	H15
VCCPLC	G17
VCCPLD	J16
VCCPLE	AH17
VCCPLF	AC16
VCCPLG	AH14
VCCPLH	AD15
VCOMPLA	F14
VCOMPLB	J15
VCOMPLC	F17
VCOMPLD	H16
VCOMPLE	AF17
VCOMPLF	AD16
VCOMPLG	AF14
VCOMPLH	AB15
VPUMP	G24

FG1152



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

Revision	Changes	Page
Revision 10 (continued)	The "TRST" section was updated.	2-107
	The "Global Set Fuse" section was added.	2-109
	A footnote was added to "FG896" for the AX2000 regarding pins AB1, AE2, G1, and K2.	3-52
	Pinouts for the AX250, AX500, and AX1000 were added for "CQ352".	3-98
	Pinout for the AX1000 was added for "CG624".	3-115
Revision 9 (v2.1)	Table 2-79 was updated.	2-69
	The "Low Power Mode" section was updated.	2-106
Revision 8 (v2.0)	Table 1 has been updated.	i
	The "Ordering Information" section has been updated.	ii
	The "Device Resources" section has been updated.	ii
	The "Temperature Grade Offerings" section is new.	iii
	The "Speed Grade and Temperature Grade Matrix" section has been updated.	iii
	Table 2-9 has been updated.	2-12
	Table 2-10 has been updated.	2-12
	Table 2-1 has been updated.	2-1
	Table 2-2 has been updated.	2-1
	Table 2-3 has been updated.	2-2
	Table 2-4 has been updated.	2-3
	Table 2-5 has been updated.	2-4
	The "Power Estimation Example" section has been updated.	2-5
	The "Thermal Characteristics" section has been updated.	2-6
	The "Package Thermal Characteristics" section has been updated.	2-6
	The "Timing Characteristics" section has been updated.	2-7
	The "Pin Descriptions" section has been updated.	2-9
	Timing numbers have been updated from the "3.3 V LVTTL" section to the "Timing Characteristics" section. Many AC Loads were updated as well.	2-25 to 2-59
	Timing characteristics for the "Hardwired Clocks" and "Routed Clocks" sections were updated.	2-66, 2-68
	Table 2-89 to Table 2-92 and Table 2-98 to Table 2-99 were updated.	2-90 to 2-93, 2-102 to 2-103
	The following sections were updated: "Low Power Mode", "Interface", "Data Registers (DRs)", "Security", "Silicon Explorer II Probe Interface", and "Programming"	2-106 to 2-110
	In the "PQ208" (AX500) section, pins 2, 52, and 156 changed from V_{CCDA} to V_{CCA}. For pins 170 and 171, the I/O names refer to pair 23 instead of 24.	3-84